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(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
14 October 2004 (14.10.2004)

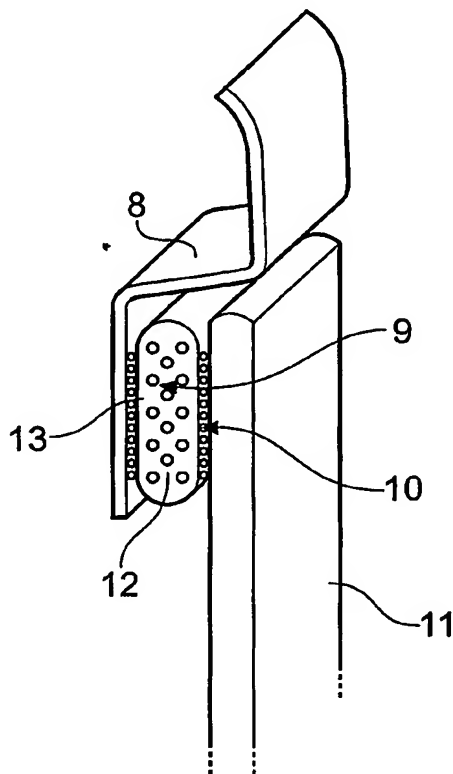
PCT

(10) International Publication Number
WO 2004/087826 A2

- (51) International Patent Classification⁷: C09J 5/00, 5/08, B60J 10/02, C08J 9/32
- (21) International Application Number: PCT/GB2004/001366
- (22) International Filing Date: 31 March 2004 (31.03.2004)
- (25) Filing Language: English
- (26) Publication Language: English
- (30) Priority Data:
0307504.1 1 April 2003 (01.04.2003) GB
0325658.3 4 November 2003 (04.11.2003) GB
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- (81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN,
CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI,
GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE,
KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD,
MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG,
PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM,
TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM,
ZW.
- (84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, GH,
[Continued on next page]

(54) Title: METHOD AND APPARATUS FOR BONDING AND DEBONDING ADHESIVE INTERFACE SURFACES

(57) Abstract: The present invention relates to a system and a method of improving the debonding of two or more surfaces together. The invention utilises thermoexpandable microspheres and thermal energy to debond interfaces in an adhesive system or as vehicle carriers. It also discloses a method of curing the adhesive system prior to the debonding step so that the same adhesive system may be used for both phases. It is especially useful in the automotive industry for end of vehicle life dismantling.



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GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Declaration under Rule 4.17:

— of inventorship (Rule 4.17(iv)) for US only

Published:

— without international search report and to be republished upon receipt of that report

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